

AMENDMENT(S) TO THE SPECIFICATION

Please replace the paragraph beginning at page 3, line 2, with the following rewritten paragraph:

Referring first to Figure 1, there is shown an MCM package comprised of an organic or other substrate 10 which contains suitable conductive vias (not shown) connecting conductive electrodes such as electrodes 13, 14, 15 on the top of substrate 10 to respective BGA solder balls on the bottom of the substrate, such as BGA solder balls 16, 17 and 18. Two semiconductor die 20 and 21 are mounted on the substrate 10 and may be flip-chip power MOSFET die having their source contacts and gate contacts on the bottom of the die and in contact, through suitable vias, with appropriate ones of the solder balls 16, 17 and 18. The tops of die 20 and 21 are immersed in "liquid metal" (eg-e.g. copper or silver powder filled epoxy) top contacts 30 and 31 which are conductive and electrically insulated from one another by insulation dams 32, 33, 34. The bottoms of chips 20 and 21 are further insulated by insulation underfill 35 and 36. The top contacts 30 and 31 are connected to the drain electrodes 22 of die 20 and 21 (which are vertical conduction devices) respectively and are connected to suitable contacts 13 (DRAIN CONNECTION) on the top of substrate 10 and then to suitable bottom solder balls 16, 17, 18.